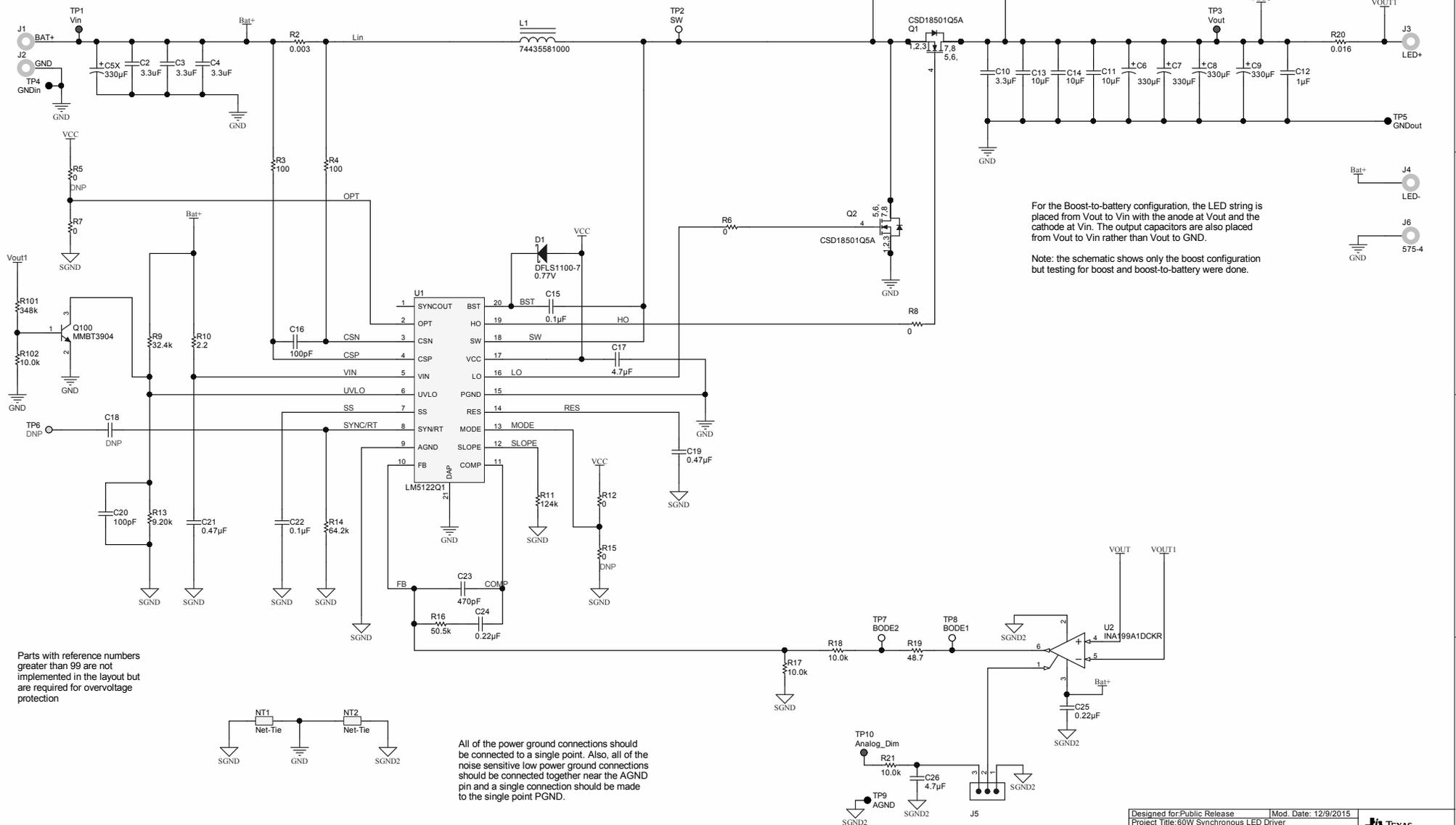


Vin = 8V to 20V DC

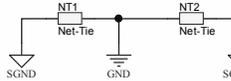
3-4 LEDs @ 3A



For the Boost-to-battery configuration, the LED string is placed from Vout to Vin with the anode at Vout and the cathode at Vin. The output capacitors are also placed from Vout to Vin rather than Vout to GND.

Note: the schematic shows only the boost configuration but testing for boost and boost-to-battery were done.

Parts with reference numbers greater than 99 are not implemented in the layout but are required for overvoltage protection



All of the power ground connections should be connected to a single point. Also, all of the noise sensitive low power ground connections should be connected together near the AGND pin and a single connection should be made to the single point PGND.

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